PCN N	20181212001.1					PCI	PCN Date:		Dec 13, 2018	
Title:	New 5x5 BG/	4 tray	ys for Select Devices							
Customer Contact: PCN A			N Manager			Dept:	Q	Quality Services		
Propo	sed 1 st Ship Da	ate:	e: Mar 13, 2019							
Chang	је Туре:									
Assembly Site					Design	Design			Wa	afer Bump Site
Assembly Process				Data Sh	Data Sheet			Wa	afer Bump Material	
Assembly Materials				Part nu	Part number change			Wa	afer Bump Process	
Mechanical Specification				Test Site				Wa	afer Fab Site	
Packing/Shipping/Labeling				Test Process				Wa	afer Fab Materials	
								Wa	afer Fab Process	
PCN Details										
Description of Change:										
Texas Instruments is pleased to announce the qualification of a new tray for select 5x5 BGA package devices in the Product Affected section below. A comparison summary of the differences are as follows:										

5x5 BGA Tray Change

5X5 BOA Tray Change						
What	From	То				
Stock #/Supplier	4200815/Ohkawa	4224682/KMH Hitech				
Weight	231.5 grams	231.4 grams				
Surface Resistivity	10^5 - 10^8 ohm/sq.	10^5 - 10^8 ohm/sq.				
Package Size	5x5	5x5				
Package Type	BGA	BGA				
Temperature Rating	150C	150C				
Matrix (Column x Rows)	10x25	16x36				
Fence Design	Fillet	Fillet				
Raw material	Carbon Powder	Carbon fiber				
Color	Black	Black				

Dimensional	Tray	Comparison

Items Description	42	200815 (Ohkav	va)	422	Remarks		
	DIM	Upper Limits	Lower Limits	DIM	Upper Limits	Lower Limits	
Overall Length	322.6	322.85	322.35	322.6	322.85	322.35	Same
Layout Length	315.0	31.5.25	314.75	315.0	31.5.25	314.75	Same
Layout Width	135.9	136.15	135.65	135.9	136.15	135.65	Same
Layout Length on Top Stack Frame	311.15	311.40	311.02	311.15	311.40	311.02	Same
Layout Width on Top Stack Frame	132.05	132.30	131.92	132.05	132.30	131.92	Same
Layout Length on Bottom Stack Frame	311.66	311.91	311.53	311.66	311.91	311.53	Same
Layout Width on Bottom Stack Frame	132.56	132.81	132.43	132.59	132.84	132.46	Same
End Tab Length	92.10	92.35	91.85	92.10	92.35	91.85	Same
Overall Height	7.62	7.75	7.49	7.62	7.75	7.49	Same
Stack Height (JEDEC C0-034)	1.27	1.40	1.14	2.00	2.13	1.87	Changed
Tray Matrix No.		12x30		16x36			Changed
Pitch M	12.70	12.83	12.57	8.70	8.83	8.57	Changed
Pitch M3	10.90	11.15	10.65	7.90	8.15	7.65	Changed
Pitch M1	8.15	8.28	8.02	8.75	9.00	8.50	Changed
Pitch M2	10.30	10.43	10.17	8.50	8.75	8.25	Changed
Cavity Size	5.19	5.29	5.09	5.23	5.28	5.18	Changed
Pedestal Design	Floor		Slope/Floor support			Changed	
Package seating height (Top)	2.00	2.08	1.92	1.47	1.55	1.39	Changed
Package seating height (Bottom)	1.60	1.68	1.52	1.41	1.49	1.33	Changed

Reason for Change:							
Con	Continuity of supply						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):							
Non	None						
Anticipated impact on Material Declaration							
	No Impact to the Material Declaration Material Declaration Material Declaration or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.						
Changes to product identification resulting from this PCN:							
New tray							
Product Affected:							
SN	SN65LVDS301ZQE SN65LVDS302ZQE TLV320AIC3106IZQE						

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TEVAC
IEXAS
NICTOLINAENITC
INSTRUMENTS

EQ# : A/T Site:

BGA JEDEC Tray Qualification Summary

Reference (QSS 003-008, 009-006, 014-102)

Supplier:	KMH HITECH I					
Vendor Part No:	P1010					
TI Part No:						
Weight/tray (g):	231.	231.5g				
Material:	150C N	150C MPPO				
Package Description	BGA 5.0	(yes/no)				
Package Designator:	ZXI					
Result:	Pas					
Date:			_			
I. First Article Inspect	ion Test	Pass		(Pass/Fail)		
II. Dimensional Test		Pass				
III. Manufacturability Te	est	Pass		_		
IV. Bake & Surface Resi	stivity Test	Pass		_		
V. Fit Analysis		Pass		_		
VI. Drop Test		Pass				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
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